

TITLE OF THE INVENTION

SEMICONDUCTOR MODULE AND INSULATING SUBSTRATE
THEREFOR

5 BACKGROUND OF THE INVENTION

Field of the Invention

The present invention relates to a power semiconductor module with a semiconductor device such as a power device mounted therein and, more particularly, to a structure of a mounting frame for forcing the semiconductor module into pressure contact
10 with an external heat sink.

Description of the Background Art

Fig. 9 is a cross-sectional view of a background art semiconductor module 118 shown as mounted on an external heat sink 111. The semiconductor module 118
15 comprises: an insulating substrate 117 including a ceramic plate 101, a first metal plate 102 and a second metal plate 103; a semiconductor device 105, such as a power device, mounted on the first metal plate 102 with solder 106; a case 104 having inside electrodes 109 connected through wires 107 to the semiconductor device 105 or the first metal plate 102, the case 104 being made of a thermoplastic resin such as polyphenylene sulfide
20 (PPS) and polybutylene terephthalate (PBT); a resin 108 enclosed and cured in the case 104; and a cover 110 for the case 104.

After silicone grease is applied to a surface of the second metal plate 103 for enhancement of a heat dissipating property, the case 104 and the external heat sink 111 are fastened by screws 112, whereby the pressing force of the case 104 brings the
25 insulating substrate 117 into pressure contact with the external heat sink 111.

In such a background art semiconductor module, the insulating substrate is forced into pressure contact with the external heat sink by the pressing force of the case, and the case is made of a thermoplastic resin. Thus, the case is gradually deformed by creep when used, in particular, continually in a high-temperature environment, and the pressing force of the case exerted upon the insulating substrate decreases with time. As a result, poor contact between the second metal plate and the external heat sink degrades the heat dissipating property.

SUMMARY OF THE INVENTION

A first aspect of the present invention is intended for a semiconductor module mountable on an external heat sink. According to the present invention, the semiconductor module comprises: an insulating substrate for the semiconductor module, the insulating substrate including a substrate, a first conductive pattern formed on a first main surface of the substrate which is on the opposite side from the external heat sink, and a second conductive pattern formed on a second main surface of the substrate which is on the same side as the external heat sink and for contact with the external heat sink; and a mounting frame made of metal and having a mounting surface for contact with the external heat sink, the mounting frame including a flange along a periphery thereof for engagement with a peripheral part of the insulating substrate at the first main surface, the flange pressing the peripheral part of the insulating substrate toward the external heat sink to force the insulating substrate into pressure contact with the external heat sink.

Preferably, according to a second aspect of the present invention, in the semiconductor module of the first aspect, the mounting frame further includes: a first metal plate having the mounting surface; and a second metal plate disposed on the first metal plate and having a protrusion along a periphery thereof projecting from a periphery

of the first metal plate to define the flange.

Preferably, according to a third aspect of the present invention, in the semiconductor module of the second aspect, the thickness of the first metal plate is equal to the sum of the thickness of the substrate and the thickness of the second conductive pattern. The thickness of the second metal plate is equal to the thickness of the first metal plate.

Preferably, according to a fourth aspect of the present invention, in the semiconductor module of any one of the first to third aspects, the insulating substrate further includes a third conductive pattern formed on the first main surface along a periphery of the substrate. The flange and the insulating substrate contact each other, with the third conductive pattern therebetween.

Preferably, according to a fifth aspect of the present invention, in the semiconductor module of the fourth aspect, the third conductive pattern is formed partially to allow part of the flange to contact the third conductive pattern. The mounting frame and the insulating substrate are bonded to each other with an adhesive filling a gap between part of the flange which is out of contact with the third conductive pattern and the first main surface.

Preferably, according to a sixth aspect of the present invention, in the semiconductor module of any one of the first to third aspects, the substrate, the first conductive pattern and the second conductive pattern of the insulating substrate have respective peripheries in alignment with each other. The flange presses the periphery of the first conductive pattern toward the external heat sink, with an insulative material between the flange and the first conductive pattern.

Preferably, according to a seventh aspect of the present invention, the semiconductor module of any one of the first to sixth aspects further comprises: a

semiconductor device mounted on the first conductive pattern; a cylindrical case disposed on a main surface of the mounting frame which is on the opposite side from the external heat sink; the case, the mounting frame and the insulating substrate defining a space surrounding the semiconductor device; and an insulative sealing material filling the space.

Preferably, according to an eighth aspect of the present invention, in the semiconductor module of the seventh aspect, the sealing material is a thermosetting resin.

A ninth aspect of the present invention is intended for an insulating substrate for a semiconductor module. According to the present invention, the insulating substrate comprises a mounting surface, the mounting surface being adapted to be forced into pressure contact with an external heat sink by a mounting frame pressing a peripheral part of the insulating substrate, the insulating substrate having a curved configuration in which a peripheral part of the mounting surface warps upwardly away from the external heat sink above a central part of the mounting surface.

In accordance with the first aspect of the present invention, the insulating substrate for the semiconductor module is forced into pressure contact with the external heat sink by the pressing force of the metal mounting frame, rather than a conventional case made of a thermoplastic resin. This causes no creep, to avoid the problem of a decreasing pressing force resulting from the deformation of the frame even after continual use in a high-temperature environment. Consequently, the semiconductor module can ensure a satisfactory heat dissipating property over a long period of time.

Additionally, the metal frame has a better heat dissipating property than the conventional case made of the thermoplastic resin. This achieves the size reduction of the semiconductor module.

The production of the flange of the mounting frame by pressing requires

various types of manufacturing management such as the management of a pressing tolerance and the management of the flatness of the mounting frame. On the other hand, in the case of the semiconductor module in accordance with the second aspect of the present invention, the management of only the tolerance of the thickness of the first metal plate is required. This facilitates the manufacturing management.

Further, the semiconductor module in accordance with the second aspect of the present invention eliminates the need to machine the flange by pressing to achieve the increase in productivity and the reduction in costs.

In accordance with the third aspect of the present invention, the thickness of the first metal plate is equal to the thickness of the second metal plate. This further facilitates the manufacturing management.

In accordance with the fourth aspect of the present invention, the flange and the insulating substrate contact each other, with the third conductive pattern therebetween. This provides further enhancement of the heat dissipating property and further size reduction of the semiconductor module.

Additionally, the semiconductor module in accordance with the fourth aspect of the present invention can insure uniform stresses applied from the flange through the third conductive pattern to the substrate, suitably preventing cracking in the substrate.

In accordance with the fifth aspect of the present invention, the adhesive may be made as thick as the third conductive pattern. Thus, if a resin in gel form is used as a sealing material for covering a semiconductor device, the adhesive prevents the sealing material from flowing out, providing the highly reliable semiconductor module.

In accordance with the sixth aspect of the present invention, the size of the insulating substrate is reduced in accordance with the elimination of an overhang extended outwardly from the periphery of the first conductive pattern. The size of the

semiconductor module itself is accordingly reduced.

In accordance with the seventh aspect of the present invention, the insulative sealing material filling the space provides a mechanical strength and ensures insulation between the metal mounting frame and the semiconductor device.

5 In accordance with the eighth aspect of the present invention, the insulating substrate is prevented from being broken by an external force applied from the direction of the second conductive pattern, before the semiconductor module is mounted on the external heat sink.

10 In accordance with the ninth aspect of the present invention, when the peripheral part of the mounting surface is forced into pressure contact with the external heat sink by the mounting frame for the mounting of the insulating substrate on the external heat sink, the central part of the mounting surface is also necessarily brought into pressure contact with the external heat sink. Thus, the ninth aspect of the present invention ensures better contact between the insulating substrate and the external heat
15 sink particularly at the central part of the mounting surface, accomplishing further enhancement of the heat dissipating property.

It is therefore an object of the present invention to provide a semiconductor module and an insulating substrate therefor which can avoid the problem of a decreasing pressing force resulting from deformation to ensure a satisfactory heat dissipating
20 property over a long period of time.

These and other objects, features, aspects and advantages of the present invention will become more apparent from the following detailed description of the present invention when taken in conjunction with the accompanying drawings.

25 BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a cross-sectional view of a semiconductor module shown as mounted on an external heat sink according to a first preferred embodiment of the present invention;

line B' → Fig. 2 is a cross-sectional view of the semiconductor module shown as mounted on the external heat sink according to a second preferred embodiment of the present invention;

line B2 → Fig. 3 is an enlarged cross-sectional view of part of a structure of the semiconductor module shown as mounted on the external heat sink according to a third preferred embodiment of the present invention;

10 Fig. 4 is an enlarged cross-sectional view of part of another structure of the semiconductor module shown as mounted on the external heat sink according to the third preferred embodiment of the present invention;

Fig. 5 is a cross-sectional view of the semiconductor module shown as mounted on the external heat sink according to a fourth preferred embodiment of the present invention;

Fig. 6 is a cross-sectional view of a structure of an insulating substrate for the semiconductor module according to a fifth preferred embodiment of the present invention;

Fig. 7 is a cross-sectional view of a structure of the insulating substrate for the semiconductor module according to a first modification of the fifth preferred embodiment of the present invention;

Fig. 8 is a cross-sectional view of a structure of the insulating substrate for the semiconductor module according to a second modification of the fifth preferred embodiment of the present invention; and

25 Fig. 9 is a cross-sectional view of a background art semiconductor module

shown as mounted on an external heat sink.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

First Preferred Embodiment

5 Fig. 1 is a cross-sectional view of a semiconductor module 18 shown as mounted on an external heat sink 11 according to a first preferred embodiment of the present invention. The semiconductor module 18 comprises an insulating substrate 17 for a semiconductor module. The insulating substrate 17 includes a ceramic plate 1, a first metal plate 2 formed on a first main surface of the ceramic plate 1 which is on the
10 opposite side from the external heat sink 11, and a second metal plate 3 formed on a second main surface of the ceramic plate 1 which is on the same side as the external heat sink 11 and for contact with the external heat sink 11.

 The semiconductor module 18 further comprises a ring-shaped metal frame 13 having a bottom surface for contact with the top surface of the external heat sink 11 and
15 serving as a mounting surface. The ring-shaped metal frame 13 has a flange 20 along an inner periphery thereof for engagement with an outer peripheral part of the insulating substrate 17 at the first main surface of the ceramic plate 1. The metal frame 13 is fastened to the external heat sink 11 by screws 12 or bonded to the external heat sink 11 with an adhesive. The flange 20 of the metal frame 13 fastened or bonded to the
20 external heat sink 11 presses the outer peripheral part of the insulating substrate 17 toward the external heat sink 11. This pressing force holds the insulating substrate 17 in pressure contact with the external heat sink 11.

 The semiconductor module 18 further comprises a semiconductor device 5, such as a power device, mounted on the first metal plate 2 with solder 6, and a cylindrical
25 hollow case 4 bonded to or fastened by screws to a main surface of the metal frame 13

which is on the opposite side from the external heat sink 11. The case 4 is made of a thermoplastic resin such as PPS and PBT, and electrodes 9 are disposed inside the case 4. The electrodes 9 are connected to the semiconductor device 5 or the first metal plate 2 through wires 7 such as aluminum fine lines.

5 The side surface of the case 4, the side surface of the flange 20 of the metal frame 13 and the top surface of the insulating substrate 17 define a space surrounding the semiconductor device 5. This space is filled with an insulative sealing material 8 which covers at least the semiconductor device 5 and the wires 7. This provides a mechanical strength and ensures insulation between the metal frame 13, the semiconductor device 5
10 and the wires 7. An example of the sealing material 8 used herein may include a thermosetting resin such as epoxy-based resin. Alternatively, silicone gel may be used as the sealing material 8 when the mechanical strength is sufficiently high. A cover 10 is bonded to or fastened by screws to the case 4, as required.

 In the semiconductor module 18 according to the first preferred embodiment of
15 the present invention, as described hereinabove, the insulating substrate 17 is forced into pressure contact with the external heat sink 11 by the pressing force of the metal frame 13, rather than the background art case 104 made of the thermoplastic resin. This causes no creep, to avoid the problem of the decreasing pressing force resulting from the deformation of the metal frame 13 even after continual use in a high-temperature
20 environment. Consequently, the semiconductor module 18 can ensure a satisfactory heat dissipating property over a long period of time.

 Additionally, the metal frame 13 has a better heat dissipating property than the background art case 104 made of the thermoplastic resin. This achieves the size reduction of the semiconductor module.

25 Furthermore, when the thermosetting resin is used as the sealing material 8, the

insulating substrate 17 is prevented from being broken by an external force applied from the direction of the second metal plate 3 before the semiconductor module 18 is mounted on the external heat sink 11.

5 Second Preferred Embodiment

sub B3 Fig. 2 is a cross-sectional view of a semiconductor module 19 shown as mounted on the external heat sink 11 according to a second preferred embodiment of the present invention. The semiconductor module 19 comprises a double-layer structure including a lower metal plate 13a having a mounting surface for contact with the external
10 heat sink 11 and an upper metal plate 13b secured on the lower metal plate 13a, in place of the metal frame 13 shown in Fig. 1. The inner periphery of the upper metal plate 13b projects inwardly from the inner periphery of the lower metal plate 13a to define a protrusion 21 corresponding to the flange 20 shown in Fig. 1.

The thickness of the lower metal plate 13a is equal to the sum of the thickness
15 of the ceramic plate 1 and the thickness of the second metal plate 3. The upper metal plate 13b may be of any thickness, but is preferably as thick as the lower metal plate 13a in consideration for the ease of manufacturing management. The remaining structure of the semiconductor module 19 according to the second preferred embodiment is identical with the corresponding structure of the semiconductor module 18 of the first preferred
20 embodiment shown in Fig. 1.

As described hereinabove, the semiconductor module 19 according to the second preferred embodiment comprises the double-layer structure including the lower metal plate 13a and the upper metal plate 13b, in place of the metal frame 13 shown in Fig. 1. The production of the flange 20 of the metal frame 13 shown in Fig. 1 by
25 pressing requires various types of manufacturing management such as the management of

a pressing tolerance and the management of the flatness of the metal frame 13. On the other hand, in the case of the semiconductor module 19 according to the second preferred embodiment, the management of only the tolerance of the thickness of the lower metal plate 13a is required. This facilitates the manufacturing management.

5 Further, the second preferred embodiment eliminates the need to machine the flange 20 by pressing to achieve the increase in productivity and the reduction in costs.

Third Preferred Embodiment

Fig. 3 is an enlarged cross-sectional view of part of a structure of the semiconductor module shown as mounted on the external heat sink 11 according to a
10 third preferred embodiment of the present invention. The semiconductor module according to the third preferred embodiment shown in Fig. 3 comprises a third metal plate 25 formed on the first main surface of the ceramic plate 1 along the outer periphery of the ceramic plate 1. The flange 20 of the metal frame 13 and the ceramic plate 1 are in
15 contact with each other, with the third metal plate 25 therebetween.

The third metal plate 25 is formed partially so that part of the flange 20 contacts the third metal plate 25. The metal frame 13 and the insulating substrate 17 are bonded to each other with an adhesive 14 filling the gap between the flange 20 and the ceramic plate 1.

20 Although the third preferred embodiment of the present invention is applied to the semiconductor module 18 of the first preferred embodiment in the above description, the third preferred embodiment may be applied to the semiconductor module 19 of the second preferred embodiment, as illustrated in Fig. 4. The remaining structure of the semiconductor module according to the third preferred embodiment is identical with the
25 corresponding structure of the semiconductor modules 18 and 19.

In the semiconductor module according to the third preferred embodiment, as described hereinabove, the metal frame 13 or the upper metal plate 13b and the ceramic plate 1 are in contact with each other, with the third metal plate 25 therebetween. This provides further enhancement of the heat dissipating property and further size reduction of the semiconductor module.

Additionally, the third preferred embodiment can insure uniform stresses applied from the flange 20 or the protrusion 21 through the third metal plate 25 to the ceramic plate 1, suitably preventing cracking in the ceramic plate 1.

Further, the adhesive 14 may be made as thick as the third metal plate 25. Thus, if a resin in gel form is used as the sealing material 8, the adhesive 14 prevents the sealing material 8 from flowing out, providing the highly reliable semiconductor module.

Fourth Preferred Embodiment

Fig. 5 is a cross-sectional view of a semiconductor module 18a shown as mounted on the external heat sink 11 according to a fourth preferred embodiment of the present invention. In the semiconductor module 18 shown in Fig. 1, for instance, the ceramic plate 1 has a peripheral overhang extended outwardly from the outer periphery of the first metal plate 2 so as to prevent the contact between the flange 20 of the metal frame 13 and the first metal plate 2 of the insulating substrate 17. In the semiconductor module 18a according to the fourth preferred embodiment, on the other hand, the peripheral overhang of the ceramic plate 1 is dispensed with so that the outer peripheries of the first metal plate 2 and the ceramic plate 1 are in alignment with each other. Additionally, the outer periphery of the second metal plate 3 is aligned with the outer periphery of the ceramic plate 1.

To prevent the metal frame 13 from contacting the first and second metal plates

2 and 3, a gap 40 is produced between the metal frame 13 and an insulating substrate 17a so that the insulative sealing material 8 flows also into the gap 40. As a result, the flange 20 of the metal frame 13 fastened by the screws to the external heat sink 11 presses the outer peripheral part of the first metal plate 2 toward the external heat sink 11, with the sealing material 8 between the flange 20 and the first metal plate 2. This pressing force holds the insulating substrate 17a in pressure contact with the external heat sink 11.

Although the fourth preferred embodiment of the present invention is applied to the semiconductor module 18 of the first preferred embodiment in the above description, the fourth preferred embodiment may be applied to the semiconductor module 19 of the second preferred embodiment.

In the semiconductor module 18a according to the fourth preferred embodiment, as described hereinabove, the outer peripheries of the ceramic plate 1 and the second metal plate 3 are aligned alignment with the outer periphery of the first metal plate 2. This reduces the size of the insulating substrate 17a in accordance with the elimination of the peripheral overhang, to accordingly reduce the width W of the semiconductor module 18a itself.

Fifth Preferred Embodiment

Fig. 6 is a cross-sectional view of a structure of an insulating substrate 15 for a semiconductor module according to a fifth preferred embodiment of the present invention. The ceramic plate 1, the first metal plate 2 and the second metal plate 3 of the insulating substrate 15 having the structure based on the insulating substrate 17 shown in Figs. 1 and 2 are of a curved configuration such that the outer peripheral part of the mounting surface for contact with the external heat sink 11 warps upwardly away from the external heat sink 11 a distance L (ranging from 0 to 300 μm) above the central part thereof.

Fig. 7 is a cross-sectional view of a structure of an insulating substrate 16 for a semiconductor module according to a modification of the fifth preferred embodiment of the present invention. The ceramic plate 1, the first metal plate 2, the second metal plate 3 and the third metal plate 25 of the insulating substrate 16 having the structure based on the insulating substrate 17 shown in Figs. 3 and 4 are of a curved configuration such that the outer peripheral part of the mounting surface warps upwardly away from the external heat sink 11 in a manner similar to the insulating substrate 15.

The ceramic plate 1, the first metal plate 2, the second metal plate 3 and the third metal plate 25 are illustrated as curved together in the above description. Alternatively, an insulating substrate 41 as shown in Fig. 8 may be provided in which only the bottom surface of the second metal plate 3 is curved convexedly. Furthermore, the fifth preferred embodiment according to the present invention may be applied to the insulating substrate 17a of the fourth preferred embodiment.

As described hereinabove, the insulating substrates 15, 16 and 41 according to the fifth preferred embodiment are shaped such that the outer peripheral part of the mounting surface warps upwardly away from the external heat sink 11 above the central part thereof, before the mounting on the external heat sink 11. When the outer peripheral part of the mounting surface is forced into pressure contact with the external heat sink 11 by the pressing force of the flange 20 or the protrusion 21 for the mounting of the semiconductor module on the external heat sink 11, the central part of the mounting surface is also necessarily brought into pressure contact with the external heat sink 11. Thus, the insulating substrates 15, 16 and 41 according to the fifth preferred embodiment ensure better contact with the external heat sink 11 particularly at the central part of the mounting surface than the insulating substrates 17 and 17a according to the first to fourth preferred embodiments, accomplishing further enhancement of the heat

dissipating property.

While the invention has been described in detail, the foregoing description is in all aspects illustrative and not restrictive. It is understood that numerous other modifications and variations can be devised without departing from the scope of the
5 invention.

10
11
12
13
14
15
16
17
18
19
20
21
22
23
24
25
26
27
28
29
30
31
32
33
34
35
36
37
38
39
40
41
42
43
44
45
46
47
48
49
50
51
52
53
54
55
56
57
58
59
60
61
62
63
64
65
66
67
68
69
70
71
72
73
74
75
76
77
78
79
80
81
82
83
84
85
86
87
88
89
90
91
92
93
94
95
96
97
98
99
100
101
102
103
104
105
106
107
108
109
110
111
112
113
114
115
116
117
118
119
120
121
122
123
124
125
126
127
128
129
130
131
132
133
134
135
136
137
138
139
140
141
142
143
144
145
146
147
148
149
150
151
152
153
154
155
156
157
158
159
160
161
162
163
164
165
166
167
168
169
170
171
172
173
174
175
176
177
178
179
180
181
182
183
184
185
186
187
188
189
190
191
192
193
194
195
196
197
198
199
200
201
202
203
204
205
206
207
208
209
210
211
212
213
214
215
216
217
218
219
220
221
222
223
224
225
226
227
228
229
230
231
232
233
234
235
236
237
238
239
240
241
242
243
244
245
246
247
248
249
250
251
252
253
254
255
256
257
258
259
260
261
262
263
264
265
266
267
268
269
270
271
272
273
274
275
276
277
278
279
280
281
282
283
284
285
286
287
288
289
290
291
292
293
294
295
296
297
298
299
300
301
302
303
304
305
306
307
308
309
310
311
312
313
314
315
316
317
318
319
320
321
322
323
324
325
326
327
328
329
330
331
332
333
334
335
336
337
338
339
340
341
342
343
344
345
346
347
348
349
350
351
352
353
354
355
356
357
358
359
360
361
362
363
364
365
366
367
368
369
370
371
372
373
374
375
376
377
378
379
380
381
382
383
384
385
386
387
388
389
390
391
392
393
394
395
396
397
398
399
400
401
402
403
404
405
406
407
408
409
410
411
412
413
414
415
416
417
418
419
420
421
422
423
424
425
426
427
428
429
430
431
432
433
434
435
436
437
438
439
440
441
442
443
444
445
446
447
448
449
450
451
452
453
454
455
456
457
458
459
460
461
462
463
464
465
466
467
468
469
470
471
472
473
474
475
476
477
478
479
480
481
482
483
484
485
486
487
488
489
490
491
492
493
494
495
496
497
498
499
500
501
502
503
504
505
506
507
508
509
510
511
512
513
514
515
516
517
518
519
520
521
522
523
524
525
526
527
528
529
530
531
532
533
534
535
536
537
538
539
540
541
542
543
544
545
546
547
548
549
550
551
552
553
554
555
556
557
558
559
560
561
562
563
564
565
566
567
568
569
570
571
572
573
574
575
576
577
578
579
580
581
582
583
584
585
586
587
588
589
590
591
592
593
594
595
596
597
598
599
600
601
602
603
604
605
606
607
608
609
610
611
612
613
614
615
616
617
618
619
620
621
622
623
624
625
626
627
628
629
630
631
632
633
634
635
636
637
638
639
640
641
642
643
644
645
646
647
648
649
650
651
652
653
654
655
656
657
658
659
660
661
662
663
664
665
666
667
668
669
670
671
672
673
674
675
676
677
678
679
680
681
682
683
684
685
686
687
688
689
690
691
692
693
694
695
696
697
698
699
700
701
702
703
704
705
706
707
708
709
710
711
712
713
714
715
716
717
718
719
720
721
722
723
724
725
726
727
728
729
730
731
732
733
734
735
736
737
738
739
740
741
742
743
744
745
746
747
748
749
750
751
752
753
754
755
756
757
758
759
760
761
762
763
764
765
766
767
768
769
770
771
772
773
774
775
776
777
778
779
780
781
782
783
784
785
786
787
788
789
790
791
792
793
794
795
796
797
798
799
800
801
802
803
804
805
806
807
808
809
810
811
812
813
814
815
816
817
818
819
820
821
822
823
824
825
826
827
828
829
830
831
832
833
834
835
836
837
838
839
840
841
842
843
844
845
846
847
848
849
850
851
852
853
854
855
856
857
858
859
860
861
862
863
864
865
866
867
868
869
870
871
872
873
874
875
876
877
878
879
880
881
882
883
884
885
886
887
888
889
890
891
892
893
894
895
896
897
898
899
900
901
902
903
904
905
906
907
908
909
910
911
912
913
914
915
916
917
918
919
920
921
922
923
924
925
926
927
928
929
930
931
932
933
934
935
936
937
938
939
940
941
942
943
944
945
946
947
948
949
950
951
952
953
954
955
956
957
958
959
960
961
962
963
964
965
966
967
968
969
970
971
972
973
974
975
976
977
978
979
980
981
982
983
984
985
986
987
988
989
990
991
992
993
994
995
996
997
998
999
1000
1001
1002
1003
1004
1005
1006
1007
1008
1009
1010
1011
1012
1013
1014
1015
1016
1017
1018
1019
1020
1021
1022
1023
1024
1025
1026
1027
1028
1029
1030
1031
1032
1033
1034
1035
1036
1037
1038
1039
1040
1041
1042
1043
1044
1045
1046
1047
1048
1049
1050
1051
1052
1053
1054
1055
1056
1057
1058
1059
1060
1061
1062
1063
1064
1065
1066
1067
1068
1069
1070
1071
1072
1073
1074
1075
1076
1077
1078
1079
1080
1081
1082
1083
1084
1085
1086
1087
1088
1089
1090
1091
1092
1093
1094
1095
1096
1097
1098
1099
1100
1101
1102
1103
1104
1105
1106
1107
1108
1109
1110
1111
1112
1113
1114
1115
1116
1117
1118
1119
1120
1121
1122
1123
1124
1125
1126
1127
1128
1129
1130
1131
1132
1133
1134
1135
1136
1137
1138
1139
1140
1141
1142
1143
1144
1145
1146
1147
1148
1149
1150
1151
1152
1153
1154
1155
1156
1157
1158
1159
1160
1161
1162
1163
1164
1165
1166
1167
1168
1169
1170
1171
1172
1173
1174
1175
1176
1177
1178
1179
1180
1181
1182
1183
1184
1185
1186
1187
1188
1189
1190
1191
1192
1193
1194
1195
1196
1197
1198
1199
1200
1201
1202
1203
1204
1205
1206
1207
1208
1209
1210
1211
1212
1213
1214
1215
1216
1217
1218
1219
1220
1221
1222
1223
1224
1225
1226
1227
1228
1229
1230
1231
1232
1233
1234
1235
1236
1237
1238
1239
1240
1241
1242
1243
1244
1245
1246
1247
1248
1249
1250
1251
1252
1253
1254
1255
1256
1257
1258
1259
1260
1261
1262
1263
1264
1265
1266
1267
1268
1269
1270
1271
1272
1273
1274
1275
1276
1277
1278
1279
1280
1281
1282
1283
1284
1285
1286
1287
1288
1289
1290
1291
1292
1293
1294
1295
1296
1297
1298
1299
1300
1301
1302
1303
1304
1305
1306
1307
1308
1309
1310
1311
1312
1313
1314
1315
1316
1317
1318
1319
1320
1321
1322
1323
1324
1325
1326
1327
1328
1329
1330
1331
1332
1333
1334
1335
1336
1337
1338
1339
1340
1341
1342
1343
1344
1345
1346
1347
1348
1349
1350
1351
1352
1353
1354
1355
1356
1357
1358
1359
1360
1361
1362
1363
1364
1365
1366
1367
1368
1369
1370
1371
1372
1373
1374
1375
1376
1377
1378
1379
1380
1381
1382
1383
1384
1385
1386
1387
1388
1389
1390
1391
1392
1393
1394
1395
1396
1397
1398
1399
1400
1401
1402
1403
1404
1405
1406
1407
1408
1409
1410
1411
1412
1413
1414
1415
1416
1417
1418
1419
1420
1421
1422
1423
1424
1425
1426
1427
1428
1429
1430
1431
1432
1433
1434
1435
1436
1437
1438
1439
1440
1441
1442
1443
1444
1445
1446
1447
1448
1449
1450
1451
1452
1453
1454
1455
1456
1457
1458
1459
1460
1461
1462
1463
1464
1465
1466
1467
1468
1469
1470
1471
1472
1473
1474
1475
1476
1477
1478
1479
1480
1481
1482
1483
1484
1485
1486
1487
1488
1489
1490
1491
1492
1493
1494
1495
1496
1497
1498
1499
1500
1501
1502
1503
1504
1505
1506
1507
1508
1509
1510
1511
1512
1513
1514
1515
1516
1517
1518
1519
1520
1521
1522
1523
1524
1525
1526
1527
1528
1529
1530
1531
1532
1533
1534
1535
1536
1537
1538
1539
1540
1541
1542
1543
1544
1545
1546
1547
1548
1549
1550
1551
1552
1553
1554
1555
1556
1557
1558
1559
1560
1561
1562
1563
1564
1565
1566
1567
1568
1569
1570
1571
1572
1573
1574
1575
1576
1577
1578
1579
1580
1581
1582
1583
1584
1585
1586
1587
1588
1589
1590
1591
1592
1593
1594
1595
1596
1597
1598
1599
1600
1601
1602
1603
1604
1605
1606
1607
1608
1609
1610
1611
1612
1613
1614
1615
1616
1617
1618
1619
1620
1621
1622
1623
1624
1625
1626
1627
1628
1629
1630
1631
1632
1633
1634
1635
1636
1637
1638
1639
1640
1641
1642
1643
1644
1645
1646
1647
1648
1649
1650
1651
1652
1653
1654
1655
1656
1657
1658
1659
1660
1661
1662
1663
1664
1665
1666
1667
1668
1669
1670
1671
1672
1673
1674
1675
1676
1677
1678
1679
1680
1681
1682
1683
1684
1685
1686
1687
1688
1689
1690
1691
1692
1693
1694
1695
1696
1697
1698
1699
1700
1701
1702
1703
1704
1705
1706
1707
1708
1709
1710
1711
1712
1713
1714
1715
1716
1717
1718
1719
1720
1721
1722
1723
1724
1725
1726
1727
1728
1729
1730
1731
1732
1733
1734
1735
1736
1737
1738
1739
1740
1741
1742
1743
1744
1745
1746
1747
1748
1749
1750
1751
1752
1753
1754
1755
1756
1757
1758
1759
1760
1761
1762
1763
1764
1765
1766
1767
1768
1769
1770
1771
1772
1773
1774
1775
1776
1777
1778
1779
1780
1781
1782
1783
1784
1785
1786
1787
1788
1789
1790
1791
1792
1793
1794
1795
1796
1797
1798
1799
1800
1801
1802
1803
1804
1805
1806
1807
1808
1809
1810
1811
1812
1813
1814
1815
1816
1817
1818
1819
1820
1821
1822
1823
1824
1825
1826
1827
1828
1829
1830
1831
1832
1833
1834
1835
1836
1837
1838
1839
1840
1841
1842
1843
1844
1845
1846
1847
1848
1849
1850
1851
1852
1853
1854
1855
1856
1857
1858
1859
1860
1861
1862
1863
1864
1865
1866
1867
1868
1869
1870
1871
1872
1873
1874
1875
1876
1877
1878
1879
1880
1881
1882
1883
1884
1885
1886
1887
1888
1889
1890
1891
1892
1893
1894
1895
1896
1897
1898
1899
1900
1901
1902
1903
1904
1905
1906
1907
1908
1909
1910
1911
1912
1913
1914
1915
1916
1917
1918
1919
1920
1921
1922
1923
1924
1925
1926
1927
1928
1929
1930
1931
1932
1933
1934
1935
1936
1937
1938
1939
1940
1941
1942
1943
1944
1945
1946
1947
1948
1949
1950
1951
1952
1953
1954
1955
1956
1957
1958
1959
1960
1961
1962
1963
1964
1965
1966
1967
1968
1969
1970
1971
1972
1973
1974
1975
1976
1977
1978
1979
1980
1981
1982
1983
1984
1985
1986
1987
1988
1989
1990
1991
1992
1993
1994
1995
1996
1997
1998
1999
2000
2001
2002
2003
2004
2005
2006
2007
2008
2009
2010
2011
2012
2013
2014
2015
2016
2017
2018
2019
2020
2021
2022
2023
2024
2025
2026
2027
2028
2029
2030
2031
2032
2033
2034
2035
2036
2037
2038
2039
2040
2041
2042
2043
2044
2045
2046
2047
2048
2049
2050
2051
2052
2053
2054
2055
2056
2057
2058
2059
2060
2061
2062
2063
2064
2065
2066
2067
2068
2069
2070
2071
2072
2073
2074
2075
2076
2077
2078
2079
2080
2081
2082
2083
2084
2085
2086
2087
2088
2089
2090
2091
2092
2093
2094
2095
2096
2097
2098
2099
2100
2101
2102
2103
2104
2105
2106
2107
2108
2109
2110
2111
2112
2113
2114
2115
2116
2117
2118
2119
2120
2121
2122
2123
2124
2125
2126
2127
2128
2129
2130
2131
2132
2133
2134
2135
2136
2137
2138
2139
2140
2141
2142
2143
2144
2145
2146
2147
2148
2149
2150
2151
2152
2153
2154
2155
2156
2157
2158
2159
2160
2161
2162
2163
2164
2165
2166
2167
2168
2169
2170
2171
2172
2173
2174
2175
2176
2177
2178
2179
2180
2181
2182
2183
2184
2185
2186
2187
2188
2189
2190
2191
2192
2193
2194
2195
2196
2197
2198
2199
2200
2201
2202
2203
2204
2205
2206
2207
2208
2209
2210
2211
2212
2213
2214
2215
2216
2217
2218
2219
2220
2221
2222
2223
2224